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Intel - EPM7192SQI160-10 Datasheet



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Understanding <u>Embedded - CPLDs (Complex</u> <u>Programmable Logic Devices)</u>

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixedfunction ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	4.5V ~ 5.5V
Number of Logic Elements/Blocks	12
Number of Macrocells	192
Number of Gates	3750
Number of I/O	124
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	160-BQFP
Supplier Device Package	160-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7192sqi160-10

Email: info@E-XFL.COM

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The MAX 7000E devices—including the EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices—have several enhanced features: additional global clocking, additional output enable controls, enhanced interconnect resources, fast input registers, and a programmable slew rate.

In-system programmable MAX 7000 devices—called MAX 7000S devices—include the EPM7032S, EPM7064S, EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices. MAX 7000S devices have the enhanced features of MAX 7000E devices as well as JTAG BST circuitry in devices with 128 or more macrocells, ISP, and an open-drain output option. See Table 4.

Feature	EPM7032 EPM7064 EPM7096	All MAX 7000E Devices	All MAX 7000S Devices
ISP via JTAG interface			\checkmark
JTAG BST circuitry			✓(1)
Open-drain output option			\checkmark
Fast input registers		~	\checkmark
Six global output enables		~	\checkmark
Two global clocks		~	\checkmark
Slew-rate control		~	\checkmark
MultiVolt interface (2)	\checkmark	~	\checkmark
Programmable register	\checkmark	~	\checkmark
Parallel expanders	\checkmark	~	\checkmark
Shared expanders	\checkmark	~	\checkmark
Power-saving mode	\checkmark	~	\checkmark
Security bit	\checkmark	~	\checkmark
PCI-compliant devices available	\checkmark	\checkmark	\checkmark

Notes:

(1) Available only in EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices only.

(2) The MultiVolt I/O interface is not available in 44-pin packages.

MAX 7000 devices contain from 32 to 256 macrocells that are combined into groups of 16 macrocells, called logic array blocks (LABs). Each macrocell has a programmable-AND/fixed-OR array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and highspeed parallel expander product terms to provide up to 32 product terms per macrocell.

The MAX 7000 family provides programmable speed/power optimization. Speed-critical portions of a design can run at high speed/full power, while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate at 50% or lower power while adding only a nominal timing delay. MAX 7000E and MAX 7000S devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. The output drivers of all MAX 7000 devices (except 44-pin devices) can be set for either 3.3-V or 5.0-V operation, allowing MAX 7000 devices to be used in mixed-voltage systems.

The MAX 7000 family is supported by Altera development systems, which are integrated packages that offer schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)— and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. The software provides EDIF 2 0 0 and 3 0 0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX-workstation-based EDA tools. The software runs on Windows-based PCs, as well as Sun SPARCstation, and HP 9000 Series 700/800 workstations.

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For more information on development tools, see the MAX+PLUS II Programmable Logic Development System & Software Data Sheet and the Quartus Programmable Logic Development System & Software Data Sheet.

Functional Description

The MAX 7000 architecture includes the following elements:

- Logic array blocks
- Macrocells
- Expander product terms (shareable and parallel)
- Programmable interconnect array
- I/O control blocks

The MAX 7000 architecture includes four dedicated inputs that can be used as general-purpose inputs or as high-speed, global control signals (clock, clear, and two output enable signals) for each macrocell and I/O pin. Figure 1 shows the architecture of EPM7032, EPM7064, and EPM7096 devices.

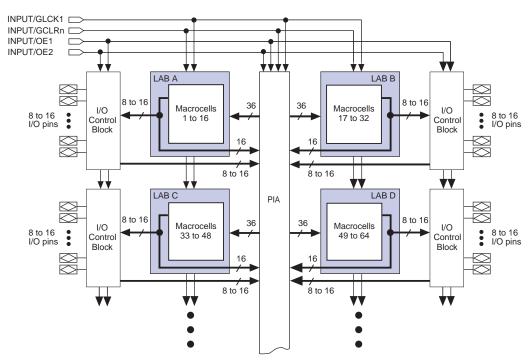


Figure 1. EPM7032, EPM7064 & EPM7096 Device Block Diagram

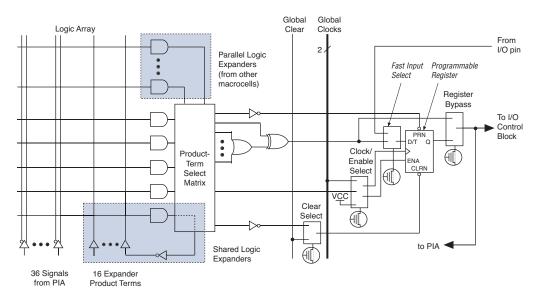
Each LAB is fed by the following signals:

- **3**6 signals from the PIA that are used for general logic inputs
- Global controls that are used for secondary register functions
- Direct input paths from I/O pins to the registers that are used for fast setup times for MAX 7000E and MAX 7000S devices

Macrocells

The MAX 7000 macrocell can be individually configured for either sequential or combinatorial logic operation. The macrocell consists of three functional blocks: the logic array, the product-term select matrix, and the programmable register. The macrocell of EPM7032, EPM7064, and EPM7096 devices is shown in Figure 3.

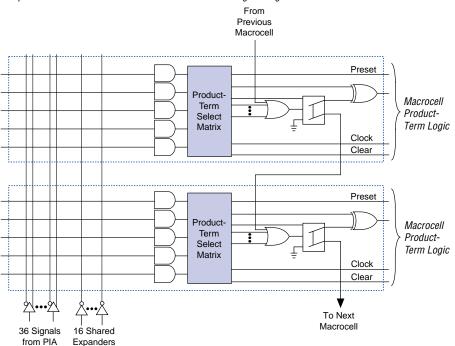
Figure 3. EPM7032, EPM7064 & EPM7096 Device Macrocell



The compiler can allocate up to three sets of up to five parallel expanders automatically to the macrocells that require additional product terms. Each set of five parallel expanders incurs a small, incremental timing delay (t_{PEXP}). For example, if a macrocell requires 14 product terms, the Compiler uses the five dedicated product terms within the macrocell and allocates two sets of parallel expanders; the first set includes five product terms and the second set includes four product terms, increasing the total delay by $2 \times t_{PEXP}$.

Two groups of 8 macrocells within each LAB (e.g., macrocells 1 through 8 and 9 through 16) form two chains to lend or borrow parallel expanders. A macrocell borrows parallel expanders from lowernumbered macrocells. For example, macrocell 8 can borrow parallel expanders from macrocell 7, from macrocells 7 and 6, or from macrocells 7, 6, and 5. Within each group of 8, the lowest-numbered macrocell can only lend parallel expanders and the highest-numbered macrocell can only borrow them. Figure 6 shows how parallel expanders can be borrowed from a neighboring macrocell.

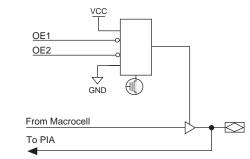
Figure 6. Parallel Expanders



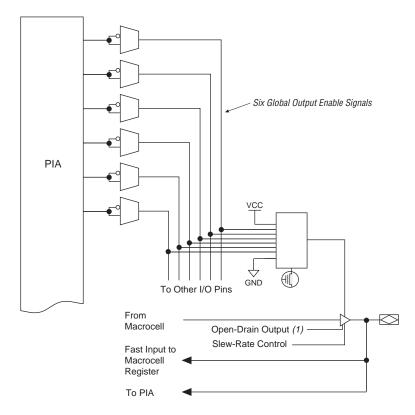
Unused product terms in a macrocell can be allocated to a neighboring macrocell.

Figure 8. I/O Control Block of MAX 7000 Devices

EPM7032, EPM7064 & EPM7096 Devices







Note:

(1) The open-drain output option is available only in MAX 7000S devices.



For more information on using the Jam language, refer to AN 122: Using Jam STAPL for ISP & ICR via an Embedded Processor.

The ISP circuitry in MAX 7000S devices is compatible with IEEE Std. 1532 specification. The IEEE Std. 1532 is a standard developed to allow concurrent ISP between multiple PLD vendors.

Programming Sequence

During in-system programming, instructions, addresses, and data are shifted into the MAX 7000S device through the TDI input pin. Data is shifted out through the TDO output pin and compared against the expected data.

Programming a pattern into the device requires the following six ISP stages. A stand-alone verification of a programmed pattern involves only stages 1, 2, 5, and 6.

- 1. *Enter ISP*. The enter ISP stage ensures that the I/O pins transition smoothly from user mode to ISP mode. The enter ISP stage requires 1 ms.
- 2. *Check ID*. Before any program or verify process, the silicon ID is checked. The time required to read this silicon ID is relatively small compared to the overall programming time.
- 3. *Bulk Erase.* Erasing the device in-system involves shifting in the instructions to erase the device and applying one erase pulse of 100 ms.
- 4. *Program*. Programming the device in-system involves shifting in the address and data and then applying the programming pulse to program the EEPROM cells. This process is repeated for each EEPROM address.
- 5. *Verify.* Verifying an Altera device in-system involves shifting in addresses, applying the read pulse to verify the EEPROM cells, and shifting out the data for comparison. This process is repeated for each EEPROM address.
- 6. *Exit ISP*. An exit ISP stage ensures that the I/O pins transition smoothly from ISP mode to user mode. The exit ISP stage requires 1 ms.

Programming Times

The time required to implement each of the six programming stages can be broken into the following two elements:

- A pulse time to erase, program, or read the EEPROM cells.
- A shifting time based on the test clock (TCK) frequency and the number of TCK cycles to shift instructions, address, and data into the device.

By combining the pulse and shift times for each of the programming stages, the program or verify time can be derived as a function of the TCK frequency, the number of devices, and specific target device(s). Because different ISP-capable devices have a different number of EEPROM cells, both the total fixed and total variable times are unique for a single device.

Programming a Single MAX 7000S Device

The time required to program a single MAX 7000S device in-system can be calculated from the following formula:

$$t_{PROG} = t_{PPULSE} + \frac{Cycle_{PTCK}}{f_{TCK}}$$
where: t_{PROG} = Programming time
 t_{PPULSE} = Sum of the fixed times to erase, program, and
verify the EEPROM cells
 $Cycle_{PTCK}$ = Number of TCK cycles to program a device
 f_{TCK} = TCK frequency

The ISP times for a stand-alone verification of a single MAX 7000S device can be calculated from the following formula:

$$t_{VER} = t_{VPULSE} + \frac{Cycle_{VTCK}}{f_{TCK}}$$
where: t_{VER} = Verify time
 t_{VPULSE} = Sum of the fixed times to verify the EEPROM cells
 $Cycle_{VTCK}$ = Number of TCK cycles to verify a device

By using an external 5.0-V pull-up resistor, output pins on MAX 7000S devices can be set to meet 5.0-V CMOS input voltages. When V_{CCIO} is 3.3 V, setting the open drain option will turn off the output pull-up transistor, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages. When V_{CCIO} is 5.0 V, setting the output drain option is not necessary because the pull-up transistor will already turn off when the pin exceeds approximately 3.8 V, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages.

Slew-Rate Control

The output buffer for each MAX 7000E and MAX 7000S I/O pin has an adjustable output slew rate that can be configured for low-noise or high-speed performance. A faster slew rate provides high-speed transitions for high-performance systems. However, these fast transitions may introduce noise transients into the system. A slow slew rate reduces system noise, but adds a nominal delay of 4 to 5 ns. In MAX 7000E devices, when the Turbo Bit is turned off, the slew rate is set for low noise performance. For MAX 7000S devices, each I/O pin has an individual EEPROM bit that controls the slew rate, allowing designers to specify the slew rate on a pin-by-pin basis.

MAX 7000 devices can be programmed on Windows-based PCs with the Altera Logic Programmer card, the Master Programming Unit (MPU), and the appropriate device adapter. The MPU performs a continuity check to ensure adequate electrical contact between the adapter and the device.

For more information, see the *Altera Programming Hardware Data Sheet*.

The Altera development system can use text- or waveform-format test vectors created with the Text Editor or Waveform Editor to test the programmed device. For added design verification, designers can perform functional testing to compare the functional behavior of a MAX 7000 device with the results of simulation. Moreover, Data I/O, BP Microsystems, and other programming hardware manufacturers also provide programming support for Altera devices.



For more information, see the Programming Hardware Manufacturers.

Programming with External Hardware

The instruction register length of MAX 7000S devices is 10 bits. Tables 10 and 11 show the boundary-scan register length and device IDCODE information for MAX 7000S devices.

Table 10. MAX 7000S Boundary-Scan Register Length							
Device	Boundary-Scan Register Length						
EPM7032S	1 (1)						
EPM7064S	1 (1)						
EPM7128S	288						
EPM7160S	312						
EPM7192S	360						
EPM7256S	480						

Note:

 This device does not support JTAG boundary-scan testing. Selecting either the EXTEST or SAMPLE/PRELOAD instruction will select the one-bit bypass register.

Table 11. 32	Table 11. 32-Bit MAX 7000 Device IDCODE Note (1)												
Device	Device IDCODE (32 Bits)												
	Version (4 Bits)	Part Number (16 Bits)	Manufacturer's Identity (11 Bits)	1 (1 Bit) (2)									
EPM7032S	0000	0111 0000 0011 0010	00001101110	1									
EPM7064S	0000	0111 0000 0110 0100	00001101110	1									
EPM7128S	0000	0111 0001 0010 1000	00001101110	1									
EPM7160S	0000	0111 0001 0110 0000	00001101110	1									
EPM7192S	0000	0111 0001 1001 0010	00001101110	1									
EPM7256S	0000	0111 0010 0101 0110	00001101110	1									

Notes:

(1) The most significant bit (MSB) is on the left.

(2) The least significant bit (LSB) for all JTAG IDCODEs is 1.

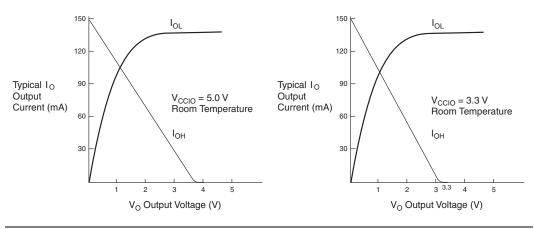
MAX 7000 Programmable Logic Device Family Data Sheet

Notes to tables:

- (1) See the Operating Requirements for Altera Devices Data Sheet.
- (2) Minimum DC input voltage on I/O pins is -0.5 V and on 4 dedicated input pins is -0.3 V. During transitions, the inputs may undershoot to -2.0 V or overshoot to 7.0 V for input currents less than 100 mA and periods shorter than 20 ns.
- (3) Numbers in parentheses are for industrial-temperature-range devices.
- (4) V_{CC} must rise monotonically.
- (5) The POR time for all 7000S devices does not exceed 300 μs. The sufficient V_{CCINT} voltage level for POR is 4.5 V. The device is fully initialized within the POR time after V_{CCINT} reaches the sufficient POR voltage level.
- (6) 3.3-V I/O operation is not available for 44-pin packages.
- (7) The V_{CCISP} parameter applies only to MAX 7000S devices.
- (8) During in-system programming, the minimum DC input voltage is -0.3 V.
- (9) These values are specified under the MAX 7000 recommended operating conditions in Table 14 on page 26.
- (10) The parameter is measured with 50% of the outputs each sourcing the specified current. The I_{OH} parameter refers to high-level TTL or CMOS output current.
- (11) The parameter is measured with 50% of the outputs each sinking the specified current. The I_{OL} parameter refers to low-level TTL, PCI, or CMOS output current.
- (12) When the JTAG interface is enabled in MAX 7000S devices, the input leakage current on the JTAG pins is typically -60 μA.
- (13) Capacitance is measured at 25° C and is sample-tested only. The OE1 pin has a maximum capacitance of 20 pF.

Figure 11 shows the typical output drive characteristics of MAX 7000 devices.

Figure 11. Output Drive Characteristics of 5.0-V MAX 7000 Devices



Timing Model

MAX 7000 device timing can be analyzed with the Altera software, with a variety of popular industry-standard EDA simulators and timing analyzers, or with the timing model shown in Figure 12. MAX 7000 devices have fixed internal delays that enable the designer to determine the worst-case timing of any design. The Altera software provides timing simulation, point-to-point delay prediction, and detailed timing analysis for a device-wide performance evaluation.

Tables 19 through 26 show the MAX 7000 and MAX 7000E AC $\,$ operating conditions.

Symbol	Parameter	Conditions	-6 Speed Grade		-7 Speed Grade		Unit
			Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5	ns
t _{SU}	Global clock setup time		5.0		6.0		ns
t _H	Global clock hold time		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input	(2)	2.5		3.0		ns
t _{FH}	Global clock hold time of fast input	(2)	0.5		0.5		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.0		4.5	ns
t _{CH}	Global clock high time		2.5		3.0		ns
t _{CL}	Global clock low time		2.5		3.0		ns
t _{ASU}	Array clock setup time		2.5		3.0		ns
t _{AH}	Array clock hold time		2.0		2.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		6.5		7.5	ns
t _{ACH}	Array clock high time		3.0		3.0		ns
t _{ACL}	Array clock low time		3.0		3.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(3)	3.0		3.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		ns
t _{CNT}	Minimum global clock period			6.6		8.0	ns
^f сnт	Maximum internal global clock frequency	(5)	151.5		125.0		MHz
t _{ACNT}	Minimum array clock period			6.6		8.0	ns
facnt	Maximum internal array clock frequency	(5)	151.5		125.0		MHz
f _{MAX}	Maximum clock frequency	(6)	200		166.7		MHz

Symbol	Parameter	Conditions	Speed	Grade -6	Speed (Unit	
			Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.4		0.5	ns
t _{IO}	I/O input pad and buffer delay			0.4		0.5	ns
t _{FIN}	Fast input delay	(2)		0.8		1.0	ns
t _{SEXP}	Shared expander delay			3.5		4.0	ns
t _{PEXP}	Parallel expander delay			0.8		0.8	ns
t _{LAD}	Logic array delay			2.0		3.0	ns
t _{LAC}	Logic control array delay			2.0		3.0	ns
t _{IOE}	Internal output enable delay	(2)				2.0	ns
t _{OD1}	Output buffer and pad delay Slow slew rate = off, $V_{CCIO} = 5.0 V$	C1 = 35 pF		2.0		2.0	ns
t _{OD2}	Output buffer and pad delay Slow slew rate = off, V_{CCIO} = 3.3 V	C1 = 35 pF (7)		2.5		2.5	ns
t _{OD3}	Output buffer and pad delay Slow slew rate = on, V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		7.0		7.0	ns
t _{ZX1}	Output buffer enable delay Slow slew rate = off, $V_{CCIO} = 5.0 V$	C1 = 35 pF		4.0		4.0	ns
t _{ZX2}	Output buffer enable delay Slow slew rate = off, $V_{CCIO} = 3.3 \text{ V}$	C1 = 35 pF (7)		4.5		4.5	ns
t _{ZX3}	Output buffer enable delay Slow slew rate = on $V_{CCIO} = 5.0 V \text{ or } 3.3 V$	C1 = 35 pF (2)		9.0		9.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0	ns
t _{SU}	Register setup time		3.0		3.0		ns
t _H	Register hold time		1.5		2.0		ns
t _{FSU}	Register setup time of fast input	(2)	2.5		3.0		ns
t _{FH}	Register hold time of fast input	(2)	0.5		0.5		ns
t _{RD}	Register delay			0.8		1.0	ns
t _{COMB}	Combinatorial delay			0.8		1.0	ns
t _{IC}	Array clock delay			2.5		3.0	ns
t _{EN}	Register enable time			2.0		3.0	ns
t _{GLOB}	Global control delay			0.8		1.0	ns
t _{PRE}	Register preset time			2.0		2.0	ns
t _{CLR}	Register clear time			2.0		2.0	ns
t _{PIA}	PIA delay			0.8		1.0	ns
t _{LPA}	Low-power adder	(8)		10.0		10.0	ns

Symbol	Parameter	Conditions	Speed Grade						
			MAX 700	0E (-10P)		00 (-10) Doe (-10)			
			Min	Max	Min	Max			
t _{IN}	Input pad and buffer delay			0.5		1.0	ns		
t _{IO}	I/O input pad and buffer delay			0.5		1.0	ns		
t _{FIN}	Fast input delay	(2)		1.0		1.0	ns		
t _{SEXP}	Shared expander delay			5.0		5.0	ns		
t _{PEXP}	Parallel expander delay			0.8		0.8	ns		
t _{LAD}	Logic array delay			5.0		5.0	ns		
t _{LAC}	Logic control array delay			5.0		5.0	ns		
t _{IOE}	Internal output enable delay	(2)		2.0		2.0	ns		
t _{OD1}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		1.5		2.0	ns		
t _{OD2}	Output buffer and pad delay Slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF (7)		2.0		2.5	ns		
t _{OD3}	Output buffer and pad delay Slow slew rate = on $V_{CCIO} = 5.0 V \text{ or } 3.3 V$	C1 = 35 pF (2)		5.5		6.0	ns		
t _{ZX1}	Output buffer enable delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		5.0		5.0	ns		
t _{ZX2}	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF (7)		5.5		5.5	ns		
t _{ZX3}	Output buffer enable delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		9.0		9.0	ns		
t _{XZ}	Output buffer disable delay	C1 = 5 pF		5.0		5.0	ns		
t _{SU}	Register setup time		2.0		3.0		ns		
t _H	Register hold time		3.0		3.0		ns		
t _{FSU}	Register setup time of fast input	(2)	3.0		3.0		ns		
t _{FH}	Register hold time of fast input	(2)	0.5		0.5		ns		
t _{RD}	Register delay			2.0		1.0	ns		
t _{COMB}	Combinatorial delay			2.0		1.0	ns		
t _{IC}	Array clock delay			5.0		5.0	ns		
t _{EN}	Register enable time			5.0		5.0	ns		
t _{GLOB}	Global control delay			1.0		1.0	ns		
t _{PRE}	Register preset time			3.0		3.0	ns		
t _{CLR}	Register clear time			3.0		3.0	ns		
t _{PIA}	PIA delay			1.0		1.0	ns		
t _{LPA}	Low-power adder	(8)		11.0		11.0	ns		

Table 2	23. MAX 7000 & MAX 7000E Ext	ernal Timing Param	eters Note	e (1)				
Symbol	Parameter	Conditions	Speed Grade					
			MAX 700	MAX 7000E (-12P)		MAX 7000E (-12P) MAX 7000 (-12 MAX 7000E (-1		
			Min	Max	Min	Max		
t _{PD1}	Input to non-registered output	C1 = 35 pF		12.0		12.0	ns	
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		12.0		12.0	ns	
t _{SU}	Global clock setup time		7.0		10.0		ns	
t _H	Global clock hold time		0.0		0.0		ns	
t _{FSU}	Global clock setup time of fast input	(2)	3.0		3.0		ns	
t _{FH}	Global clock hold time of fast input	(2)	0.0		0.0		ns	
t _{CO1}	Global clock to output delay	C1 = 35 pF		6.0		6.0	ns	
t _{CH}	Global clock high time		4.0		4.0		ns	
t _{CL}	Global clock low time		4.0		4.0		ns	
t _{ASU}	Array clock setup time		3.0		4.0		ns	
t _{AH}	Array clock hold time		4.0		4.0		ns	
t _{ACO1}	Array clock to output delay	C1 = 35 pF		12.0		12.0	ns	
t _{ACH}	Array clock high time		5.0		5.0		ns	
t _{ACL}	Array clock low time		5.0		5.0		ns	
t _{CPPW}	Minimum pulse width for clear and preset	(3)	5.0		5.0		ns	
t _{ODH}	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		ns	
t _{CNT}	Minimum global clock period			11.0		11.0	ns	
f _{CNT}	Maximum internal global clock frequency	(5)	90.9		90.9		MHz	
t _{ACNT}	Minimum array clock period			11.0		11.0	ns	
f _{acnt}	Maximum internal array clock frequency	(5)	90.9		90.9		MHz	
f _{MAX}	Maximum clock frequency	(6)	125.0		125.0		MHz	

Table 2	8. EPM7032S Internal T	iming Parameter	rs A	lote (1)							
Symbol	Parameter	Conditions				Speed	Grade				Unit
			-	-5 -6 -7 -10					0		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PIA}	PIA delay	(7)		1.1		1.1		1.4		1.0	ns
t _{LPA}	Low-power adder	(8)		12.0		10.0		10.0		11.0	ns

Notes to tables:

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 29 and 30 show the EPM7064S AC operating conditions.

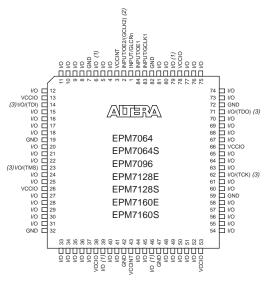
Symbol	Parameter	Conditions				Speed	Grade)			Unit
			-	5	-6		-7		-10		1
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t _{SU}	Global clock setup time		2.9		3.6		6.0		7.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		2.5		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.5		0.5		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		3.2		4.0		4.5		5.0	ns
t _{CH}	Global clock high time		2.0		2.5		3.0		4.0		ns
t _{CL}	Global clock low time		2.0		2.5		3.0		4.0		ns
t _{ASU}	Array clock setup time		0.7		0.9		3.0		2.0		ns
t _{AH}	Array clock hold time		1.8		2.1		2.0		3.0		ns

Table 39. MAX 7000 I _{CC} Equation Constants									
Device	A	В	C						
EPM7032	1.87	0.52	0.144						
EPM7064	1.63	0.74	0.144						
EPM7096	1.63	0.74	0.144						
EPM7128E	1.17	0.54	0.096						
EPM7160E	1.17	0.54	0.096						
EPM7192E	1.17	0.54	0.096						
EPM7256E	1.17	0.54	0.096						
EPM7032S	0.93	0.40	0.040						
EPM7064S	0.93	0.40	0.040						
EPM7128S	0.93	0.40	0.040						
EPM7160S	0.93	0.40	0.040						
EPM7192S	0.93	0.40	0.040						
EPM7256S	0.93	0.40	0.040						

This calculation provides an I_{CC} estimate based on typical conditions using a pattern of a 16-bit, loadable, enabled, up/down counter in each LAB with no output load. Actual I_{CC} values should be verified during operation because this measurement is sensitive to the actual pattern in the device and the environmental operating conditions.

Figure 18. 84-Pin Package Pin-Out Diagram

Package outline not drawn to scale.



84-Pin PLCC

Notes:

- (1) Pins 6, 39, 46, and 79 are no-connect (N.C.) pins on EPM7096, EPM7160E, and EPM7160S devices.
- (2) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (3) JTAG ports are available in MAX 7000S devices only.

Revision History

The information contained in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.7 supersedes information published in previous versions. The following changes were made in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.7:

Version 6.7

The following changes were made in the *MAX* 7000 *Programmable Logic Device Family Data Sheet* version 6.7:

Reference to AN 88: Using the Jam Language for ISP & ICR via an Embedded Processor has been replaced by AN 122: Using Jam STAPL for ISP & ICR via an Embedded Processor.

Version 6.6

The following changes were made in the *MAX* 7000 *Programmable Logic Device Family Data Sheet* version 6.6:

- Added Tables 6 through 8.
- Added "Programming Sequence" section on page 17 and "Programming Times" section on page 18.

Version 6.5

The following changes were made in the *MAX* 7000 *Programmable Logic Device Family Data Sheet* version 6.5:

Updated text on page 16.

Version 6.4

The following changes were made in the *MAX* 7000 *Programmable Logic Device Family Data Sheet* version 6.4:

Added Note (5) on page 28.

Version 6.3

The following changes were made in the *MAX* 7000 *Programmable Logic Device Family Data Sheet* version 6.3:

 Updated the "Open-Drain Output Option (MAX 7000S Devices Only)" section on page 20.



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